

## METHOD FOR FORMING PATTERNS FOR SEMICONDUCTOR DEVICES

### Abstract of the Disclosure

5           A method for forming an electrically conductive layer having  
predetermined patterns for semiconductor devices includes providing a  
substrate, forming an insulation layer having OH functional groups on the  
substrate, forming a patterned polymer layer on the insulation layer, etching the  
insulation layer to create a patterned insulation layer which has the same  
10   patterns as the patterned polymer layer, stripping the patterned polymer layer to  
expose the patterned insulation layer, treating the patterned insulation layer with  
a coupling agent which reacts with the OH functional groups, treating the  
patterned insulation layer with a catalyst-containing solution in which the  
catalyst reacts with the coupling agent, and depositing electrically conductive  
15   material on the patterned insulation layer which is catalytically active.